

TOSHIBA FIELD EFFECT TRANSISTOR SILICON P CHANNEL MOS TYPE (π -MOSV)

2SJ439

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS

DC-DC CONVERTER, RELAY DRIVE AND MOTOR DRIVE APPLICATIONS

- 2.5V Gate Drive
- Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.18\Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}| = 6.0S$ (Typ.)
- Low Leakage Current : $I_{DSS} = -100\mu A$ (Max.) ($V_{DS} = -16V$)
- Enhancement-Mode : $V_{th} = -0.5 \sim -1.1V$
($V_{DS} = -10V, I_D = -1mA$)

MAXIMUM RATINGS ($T_a = 25^\circ C$)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V_{DSS}	-16	V
Drain-Gate Voltage ($R_{GS} = 20k\Omega$)		V_{DGR}	-16	V
Gate-Source Voltage		V_{GSS}	± 8	V
Drain Current	DC	I_D	-5	A
	Pulse	I_{DP}	-20	
Drain Power Dissipation ($T_c = 25^\circ C$)		P_D	20	W
Channel Temperature		T_{ch}	150	$^\circ C$
Storage Temperature Range		T_{stg}	-55~150	$^\circ C$

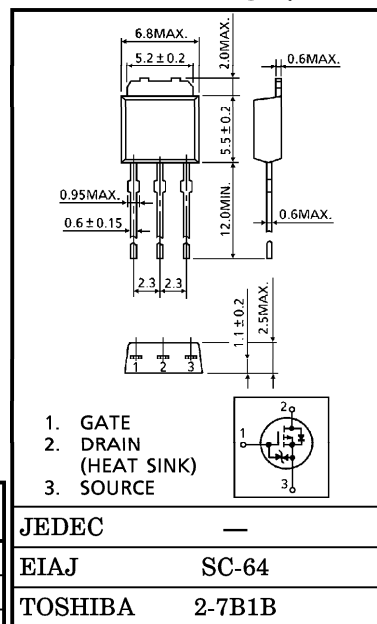
THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	6.25	$^\circ C/W$
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	125	$^\circ C/W$

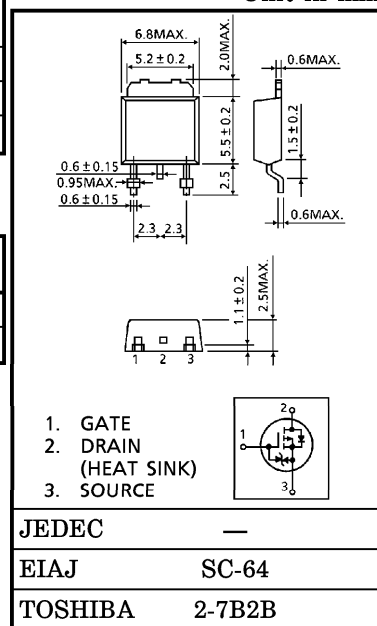
**This transistor is an electrostatic sensitive device.
Please handle with caution.**

INDUSTRIAL APPLICATIONS

Unit in mm



Unit in mm



Weight : 0.36g

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		IGSS	VGS = ±6.5V, VDS = 0V	—	—	±10	μA
Drain Cut-off Current		IDSS	VDS = -16V, VGS = 0V	—	—	-100	μA
Drain-Source Breakdown Voltage		V(BR)DSS	ID = -10mA, VGS = 0V	-16	—	—	V
Gate Threshold Voltage		Vth	VDS = -10V, ID = -1mA	-0.5	—	-1.1	V
Drain-Source ON Resistance		RDS(ON)	VGS = -2.5V, ID = -2.5A	—	0.18	0.28	Ω
			VGS = -4V, ID = -2.5A	—	0.14	0.2	
Forward Transfer Admittance		Yfs	VDS = -10V, ID = -2.5A	3.0	6.0	—	S
Input Capacitance		Ciss	VDS = -10V, VGS = 0V, f = 1MHz	—	1050	—	pF
Reverse Transfer Capacitance		Crss		—	120	—	
Output Capacitance		Coss		—	460	—	
Switching Time	Rise Time	tr	<p>VGS: 0V, -5V ID = -2.5A RL = 3.2Ω VDD ≐ -8V VIN : tr, tf < 5ns, Duty ≦ 1%, tw = 10μs</p>	—	80	—	ns
	Turn-on Time	ton		—	100	—	
	Fall Time	tf		—	250	—	
	Turn-off Time	t _{off}		—	550	—	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Qg	VDD ≐ -16V, VGS = -5V, ID = -5A	—	24	—	nC
Gate-Source Charge		Qgs		—	16	—	
Gate-Drain ("Miller") Charge		Qgd		—	8	—	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	IDR	—	—	—	-5	A
Pulse Drain Reverse Current	IDRP	—	—	—	-20	A
Diode Forward Voltage	VDSF	IDR = -5A, VGS = 0V	—	—	1.7	V
Reverse Recovery Time	t _{rr}	IDR = -5A, VGS = 0V	—	120	—	ns
Reverse Recovered Charge	Q _{rr}	dIDR / dt = 50A / μs	—	0.12	—	μC

MARKING

